

ABSTRACT OF THE DISCLOSURE

A method of making a microelectronic assembly comprises providing a first side assembly juxtaposed with a second side assembly and a first resilient element disposed therebetween. Leads extend between the first side assembly and the second side assembly. A compressive force is applied to the juxtaposed assemblies so as to compress the first resilient element and the compressive force is at least partially released so as to allow the first resilient element to expand, thereby moving one or both of the first side assembly and the second side assembly to deform the leads.

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